

**EVASOL  
J3-1001-UG**

Sn-Ag-Cu type lead free solder paste  
Non cleaning

**<Feature>**

This product has wettability, low-void, stability on storage printing, electronic reliability, and colorless transparency residue of flux.

Table. Characteristic

Items		Characteristic	Test method
Alloy composition (%)		Sn:balance, Ag: 3.0±0.1 Cu: 0.50±0.05	Allowable impurity level is based on JIS Z 3282 class-A
Solidus temperature (°C)		217	DSC (Differential Scanning Calorimetry)
Liquidus temperature (°C)		220	
Powder particle size (µm)		38 ~ 20	JIS Z 8801
Flux contents (mass %)		12.0 ± 1.0	JIS Z 3197 8.1.2
Halide contents (mass %)		Less than 0.01	JIS Z 3197 8.1.4.2.1
Copper plate corrosion test		Passed	JIS Z 3197 8.4.1
Copper mirror test		Passed	JIS Z 3197 8.4.2
Insulation resistance test (Ω)		More than 5 × 10 <sup>8</sup>	JIS Z 3197 8.5.3 85°C-85RH%, 168h, in chamber
Voltage-applied moisture resistance test	Insulation resistance test (Ω)	More than 5 × 10 <sup>8</sup>	JIS Z 3197 8.5.4 85°C-85RH%, 1000h, 100VDC, in chamber
	Migration	Passed	
Aqueous solution resistance test (Ω m)		More than 1,000	JIS Z 3197 8.1.1
Dryness test		Passed	JIS Z 3197 8.5.1
Spreading factor test (%)		More than 75	JIS Z 3197 8.3.1.1
Viscosity test(Pa·s)		190 ± 30	Malcom PCU-2 10rpm, 3minutes
Thixotropic index test		0.50 ± 0.10	Calculation